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Vishay Siliconix

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)			
100	0.0056 at V _{GS} = 10 V	131	53.5 nC			
	0.0062 at V _{GS} = 7.5 V	129	33.3 110			



Ordering Information:

SUM70060E-GE3 (lead (Pb)-free and halogen-free)

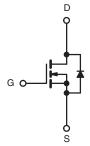
FEATURES

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Power supplies:
 - Uninterruptible power supplies
 - AC/DC switch-mode power supplies
 - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- · Battery management



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		V _{DS}	100	V		
Gate-Source Voltage	V _{GS}	± 20	- V			
Continuous Drain Current /T 150 °C)	T _C = 25 °C		131			
Continuous Drain Current (T _J = 150 °C)	T _C = 125 °C	- I _D	75			
Pulsed Drain Current (t = 100 μs)	I _{DM}	240	Α			
Avalanche Current Single Avalanche Energy ^a L = 0.1 mH		I _{AS}	50			
		E _{AS}	125	mJ		
Maximum Power Dissipation ^a	T _C = 25 °C	P _D	375 ^b	W		
waxiinum rowei bissipation «	T _C = 125 °C	PD PD	125 ^b	VV		
Operating Junction and Storage Temperature R	T _J , T _{stg}	-55 to +175	°C			

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W			
Junction-to-Case (Drain)	R _{thJC}	0.75	C/VV			

Notes

- a. Duty cycle ≤ 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_D=250\;\mu A$	2	-	4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$	1	-	1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 100 V, V_{GS} = 0 V, T_J = 125 °C	-	-	100		
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 175 °C	-	-	2	mA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	90	-	-	Α	
Drain-Source On-State Resistance a	П	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	-	0.0046	0.0056	Ω	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, I_D = 30 \text{ A}$	-	0.0048	0.0062		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 30 \text{ A}$	-	85	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	3330	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	-	1395	-		
Reverse Transfer Capacitance	C _{rss}		-	95	-		
Total Gate Charge ^c	Qg		-	53.5	81	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	-	14.5	-		
Gate-Drain Charge ^c	Q_{gd}		-	13.2	-		
Gate Resistance	R_g	f = 1 MHz	0.9	1.9	3.8	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	13	26		
Rise Time ^c	t _r	V_{DD} = 50 V, R_L = 1.67 Ω	-	22	44	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 30 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	27	54		
Fall Time ^c	t _f		-	9	18		
Drain-Source Body Diode Ratings at	nd Characteri	stics ^b (T _C = 25 °C)					
Pulsed Current (t = 100 μs)	I _{SM}		-	-	240	Α	
Forward Voltage ^a	V _{SD}	I _F = 30 A, V _{GS} = 0 V	-	0.86	1.4	٧	
Reverse Recovery Time	t _{rr}		-	88	176	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	$I_F = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	-	5	10	Α	
Reverse Recovery Charge	Q_{rr}	1		0.22	0.44	μC	

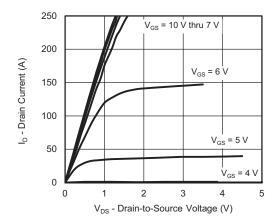
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

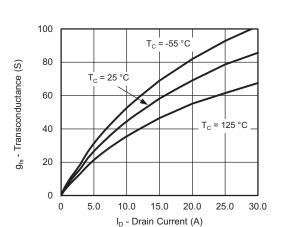
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



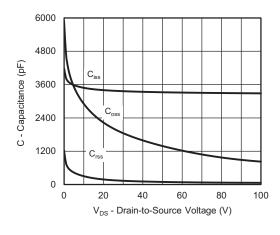
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



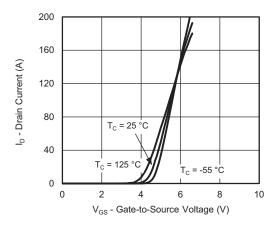
Output Characteristics



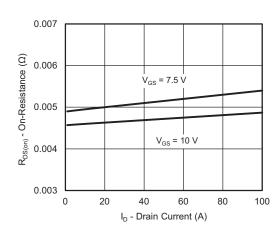
Transconductance



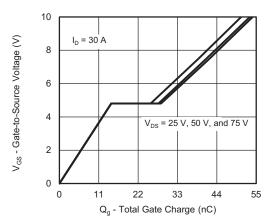
Capacitance



Transfer Characteristics



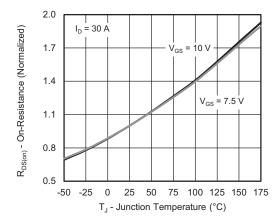
On-Resistance vs. Drain Current



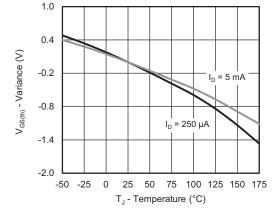
Gate Charge



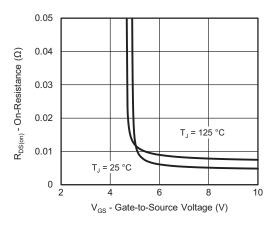
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



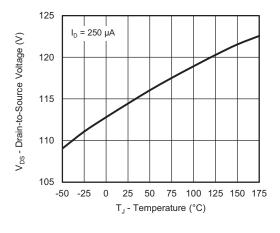
On-Resistance vs. Junction Temperature



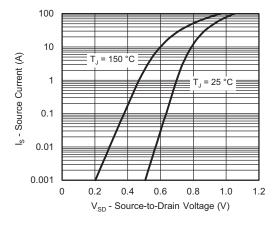
Threshold Voltage



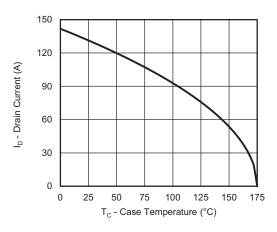
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



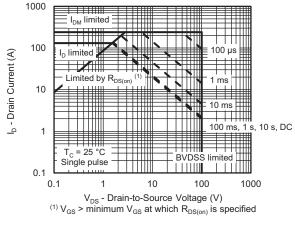
Source Drain Diode Forward Voltage

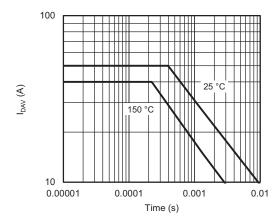


Current De-Rating



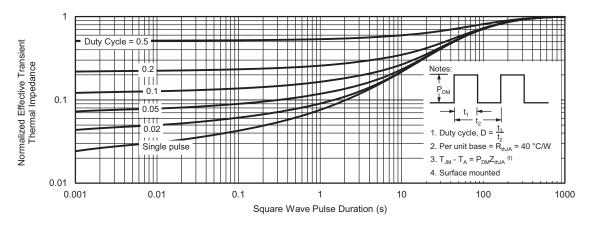
THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)





Safe Operating Area

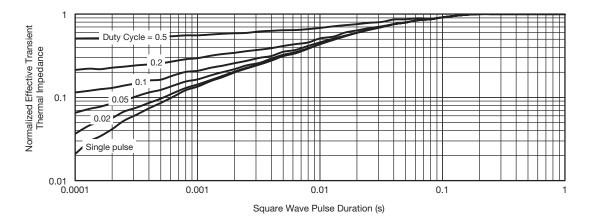
I_{DAV} vs. Time



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

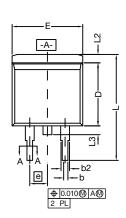
can widely vary depending on actual application parameters and operating conditions.

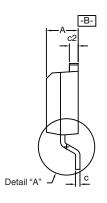
- Normalized Transient Thermal Impedance Junction to Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities

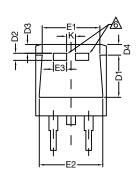
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg265383.



TO-263 (D²PAK): 3-LEAD

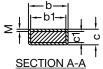








DETAIL A (ROTATED 90°)



_	,	 - -	b- o1-		ļ	ţ
2:	П			<u>T</u>	5	ပ
,	SE	СТ	ION	ΙΔ-	Ι.Δ	t

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6 This feature is for thick lead.

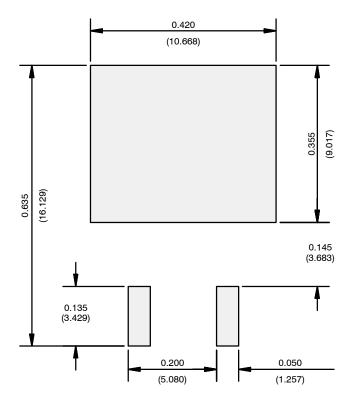
		INCHES		MILLIMETERS			
DIM.		MIN.	MAX.	MIN.	MAX.		
Α		0.160	0.190	4.064	4.826		
	b	0.020	0.039	0.508	0.990		
	b1	0.020	0.035	0.508	0.889		
	b2	0.045	0.055	1.143	1.397		
c*	Thin lead	0.013	0.018	0.330	0.457		
C	Thick lead	0.023	0.028	0.584	0.711		
c1	Thin lead	0.013	0.017	0.330	0.431		
CI	Thick lead	0.023	0.027	0.584	0.685		
	c2	0.045	0.055	1.143	1.397		
	D	0.340	0.380	8.636	9.652		
	D1	0.220	0.240	5.588	6.096		
	D2	0.038	0.042	0.965	1.067		
	D3	0.045	0.055	1.143	1.397		
	D4	0.044	0.052	1.118	1.321		
	Е	0.380	0.410	9.652	10.414		
	E1	0.245	-	6.223	=		
	E2	0.355	0.375	9.017	9.525		
	E3	0.072	0.078	1.829	1.981		
	е	0.100) BSC	2.54 BSC			
	K	0.045	0.055	1.143	1.397		
L		0.575	0.625	14.605	15.875		
L1		0.090	0.110	2.286	2.794		
	L2 0.040		0.055	1.016	1.397		
L3		0.050	0.070	1.270	1.778		
	L4	0.010) BSC	0.254 BSC			
М		-	0.002	-	0.050		
ECN: T13-0707-Rev. K, 30-Sep-13							

DWG: 5843





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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